KYOCERA Chemical Corporation
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Pastes for Flip Chip Assembly use, TAP/TNP Series

Sophisticated ACP/NCP for Several Type of Joint Assembly

Strong Points

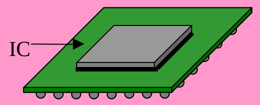
1) Enable Simple and Convenient Heat Press Bonding Process
(Rapid Curing Leads High Productivity)
2)(Neighboring electrode gap:to 20um)
Applicable for High Density Mounting with Fine Pitch
3)(Application Temperature:120 - 250°C)
Possible for Lower Temp. Joint (Joint Temp. 120 - 250°C)
4)(Non-Solvent type 1 liquid)
Non-solvent, Lead-Less, Replacement of Soldering

Application

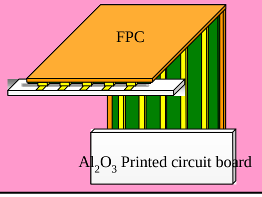
a) Flip Chip Assembly for COX etc.
b) Adhesive for Several SMD Application

Example

Flip Chip Assembly

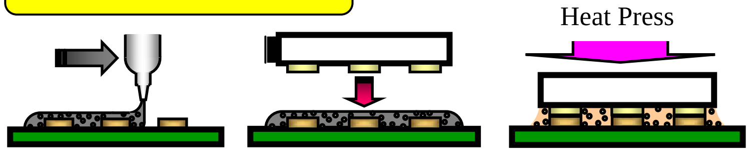


Join between PWB



Application Guide	Tape Substrate	Rigid Substrate
Application	LCD Driver, COF, CCD C-MOS Module	Memory IC, COB FC COB
NCP (No Conductive Particle)	**TNP0400**	**TNP0210**
Application	FC COF OLB	CCD Module FC COB, COG
ACP (Au Coated Particle)	**TAP0401C**	**TAP0211C**
Application	IC Card, IC Tag FC COF	Sensor FC COB
ACP (Ni Particle)	**TAP0402E**	**TAP0212E**

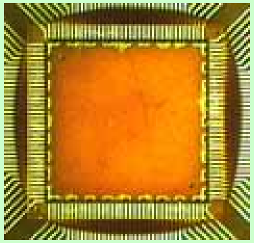
Interconnect Process



Paste Dispensing → Chip Mounting → Press and Curing

Void-Free Assembly

Flip Chip Assembly of 6*6mm
Glass Chip with 144 Au Bumps
on FPC.
Heat Tool Temperature: 240°C



Good Interconnection

Bump Material : Au
Bump size : 100x100 um
Electrode Material:Cu Plated Au
Pressure Condition:100gf/bump

Interconnection